

BYK-310 SG

Silicone-containing surface additive for solvent-free and solvent-borne coating systems, printing inks, adhesive systems and ambient-curing plastic systems with a strong reduction of the surface tension. Thermostable up to 210 °C.

Product data

Composition

Solution of a polyester-modified polydimethylsiloxane.

SVHC label-free (EU SDS)

Typical properties

The values indicated in this data sheet describe typical properties and do not constitute specification limits.

Density (20 °C):	0.91 g/ml
Non-volatile matter (10 min, 150 °C):	25 %
Solvents:	Xylene
Flash point:	25 °C

Storage and transportation

Separation or turbidity may occur at temperatures below 5 °C. Warm to 20 °C and mix well.

Applications

Coatings industry

Special features and benefits

The additive provides a strong reduction of the surface tension of coating systems. It therefore particularly improves substrate wetting and avoids cratering. Surface slip and gloss are also increased. BYK-310 SG is a thermostable silicone additive which, in contrast to conventional silicones, shows no thermal decomposition at temperatures between 150 °C and 230 °C. Consequently, when re-coating, no loss in adhesion and no surface defects occur, which can be caused by the decomposition products of conventional silicones above 150 °C.

Recommended use

The additive is particularly recommended for all solvent-borne coatings and can also be used in solvent-free systems.

Recommended levels

0.05–0.3 % additive (as supplied) based upon total formulation. In solvent-free systems up to 0.5 %.

The above recommended levels can be used for orientation. The optimum dosage should be determined by application-related test series.

Incorporation and processing instructions

The additive can be incorporated during any stage of the production process, including post-addition.

Special note

Unlike so-called silicone oils, this additive is very user-friendly. Nevertheless, it should be determined in series testing, whether foam is stabilized in certain systems. Similarly, the recoatability, the migration of silicone in stacked sheets as well as cratering should be checked.

Printing inks**Special features and benefits**

The additive provides a strong reduction of the surface tension of the systems. It therefore particularly improves substrate wetting and avoids cratering. Surface slip and gloss are also increased.

Recommended use

Recommended for all solvent-borne printing inks.

Recommended levels

0.05–0.3 % additive (as supplied) based upon total formulation.

The above recommended levels can be used for orientation. The optimum dosage should be determined by application-related test series.

Incorporation and processing instructions

The additive can be incorporated during any stage of the production process, including post-addition.

Special note

Unlike so-called silicone oils, this additive is very user-friendly. Nevertheless, it should be determined in series testing, whether foam is stabilized in certain systems. Similarly, the recoatability and cratering should be checked.

Adhesives and sealants**Special features and benefits**

BYK-310 SG is a highly effective silicone additive. It provides a strong reduction of the surface tension, thereby improving the wetting of critical substrates.

Recommended use

Recommended for improving the substrate wetting of epoxy-based adhesive systems.

Recommended levels

0.05–0.3 % additive (as supplied) based upon total formulation.

The above recommended levels can be used for orientation. The optimum dosage should be determined by application-related test series.

Incorporation and processing instructions

The additive can be incorporated during any stage of the production process, including post-addition.

Special note

Unlike so-called silicone oils, this additive is very user friendly. Nevertheless, its influence on the adhesive properties should be checked.

Ambient-curing Plastic Systems

Special features and benefits

BYK-310 SG is a highly effective silicone additive. It provides a strong reduction of the surface tension, thereby improving the wetting of critical substrates. It also exhibits high temperature stability.

Recommended use

Recommended for improving the substrate wetting of ambient-curing epoxy-based resin systems.

Recommended levels

0.05–0.3 % additive (as supplied) based upon total formulation.

The above recommended levels can be used for orientation. The optimum dosage should be determined by application-related test series.

Incorporation and processing instructions

The additive can be incorporated during any stage of the production process, including post-addition.

Special note

Unlike so-called silicone oils, this additive is very user friendly. Nevertheless, it should be determined in series testing, whether surface defects occur in certain systems.



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This issue replaces all previous versions.